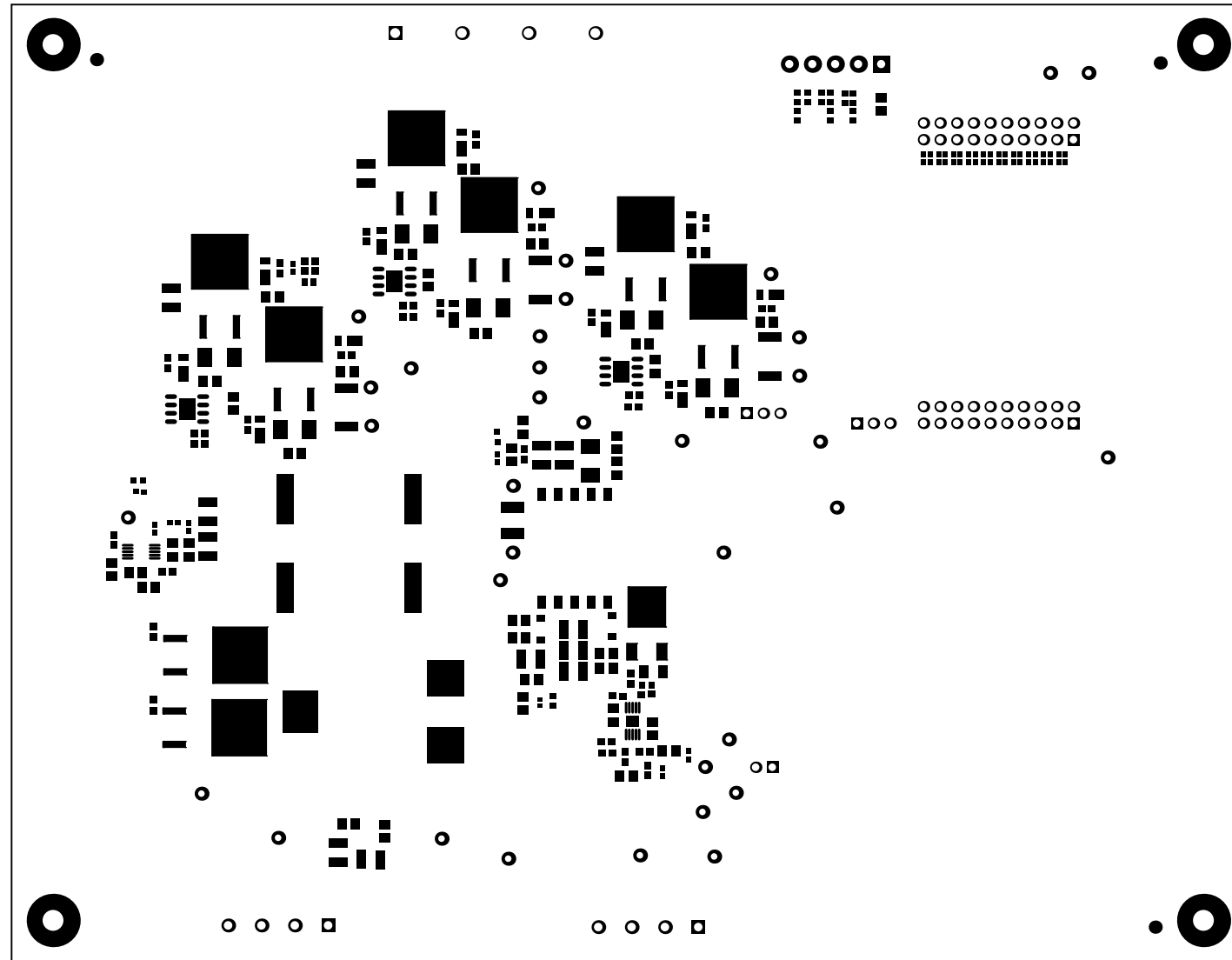
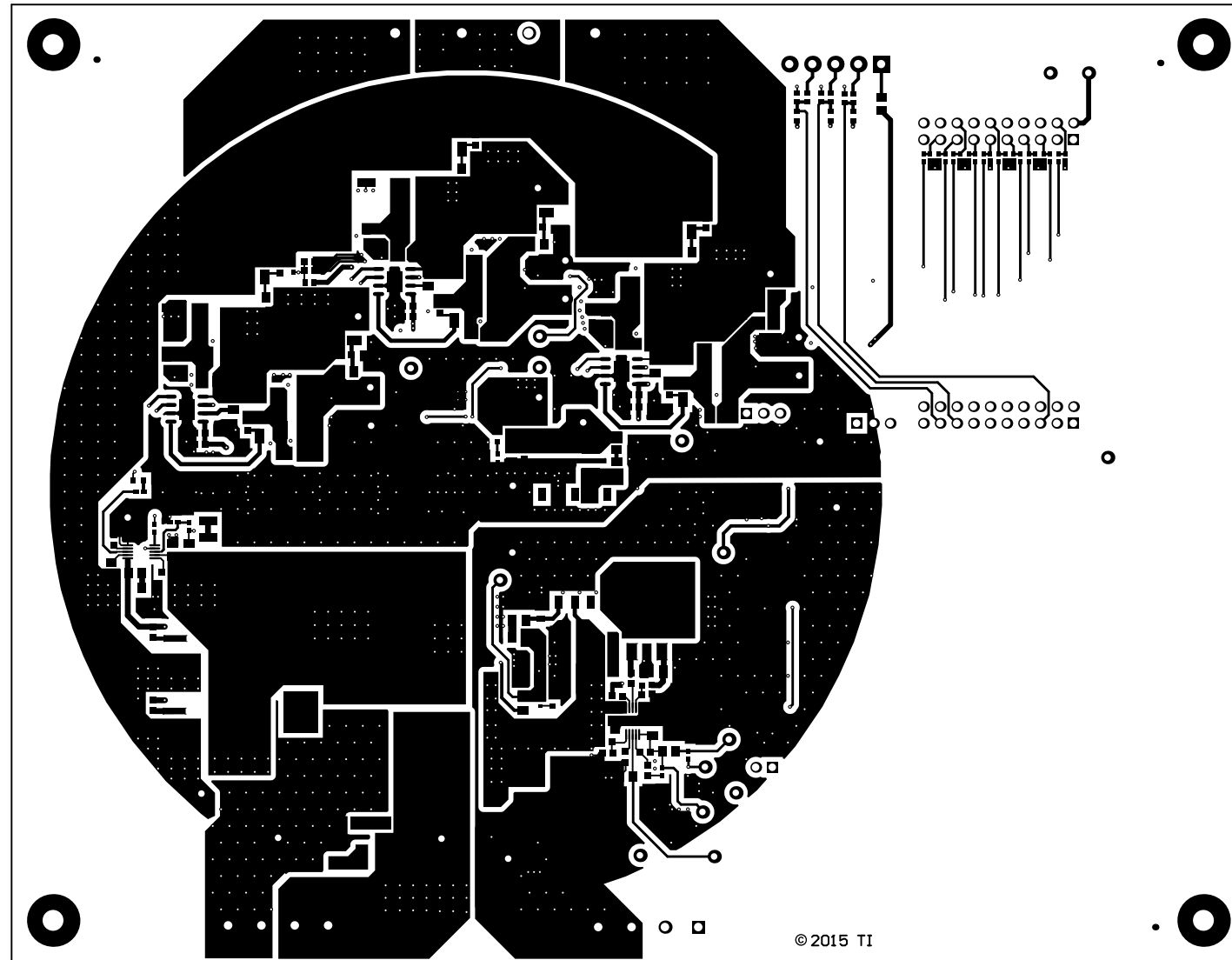


TEXAS INSTRUMENTS
TIDA-00281 E1

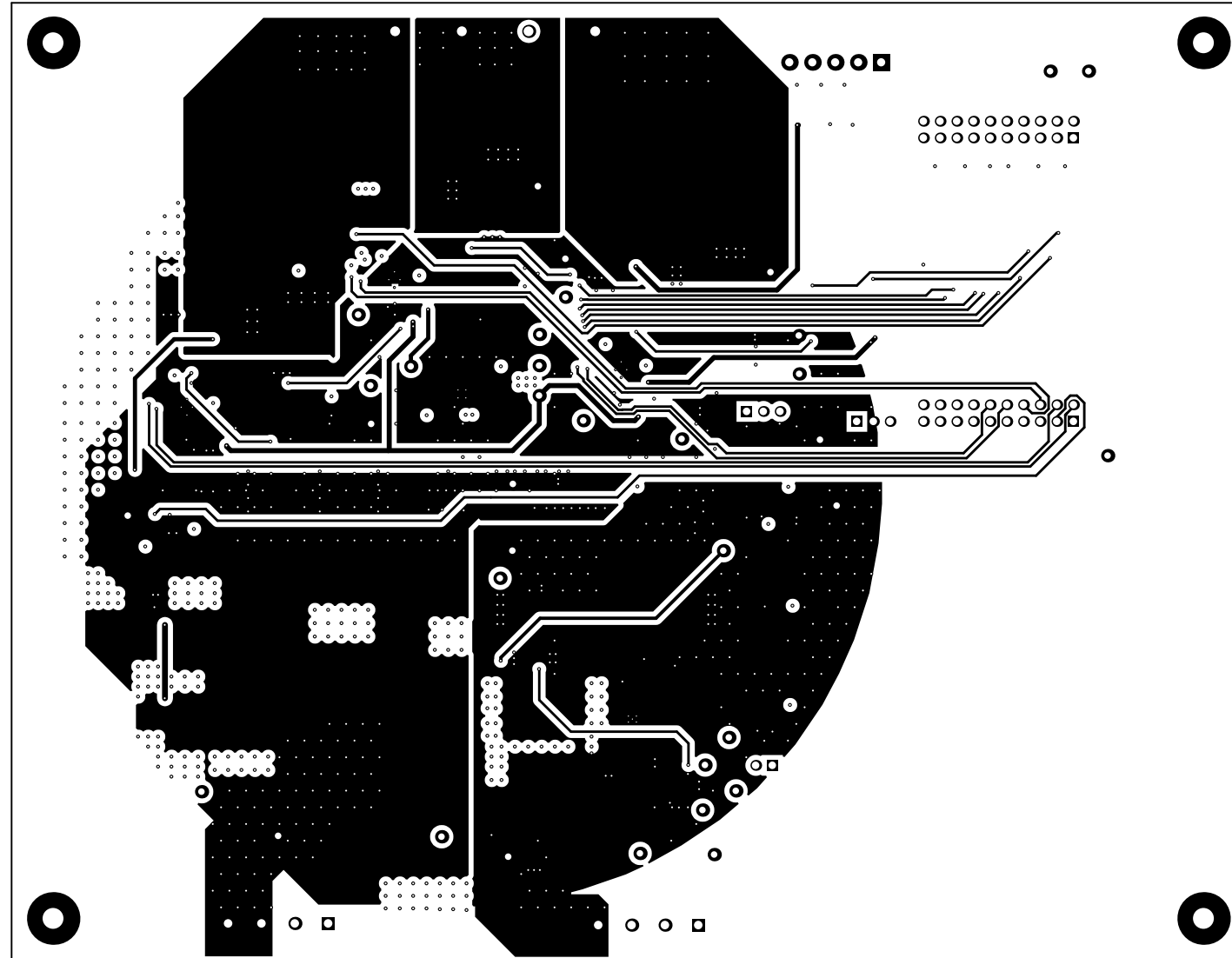
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00281		
PLOT NAME = Top Overlay	GENERATED : 10/23/2015 3:00:22 PM	TEXAS INSTRUMENTS	



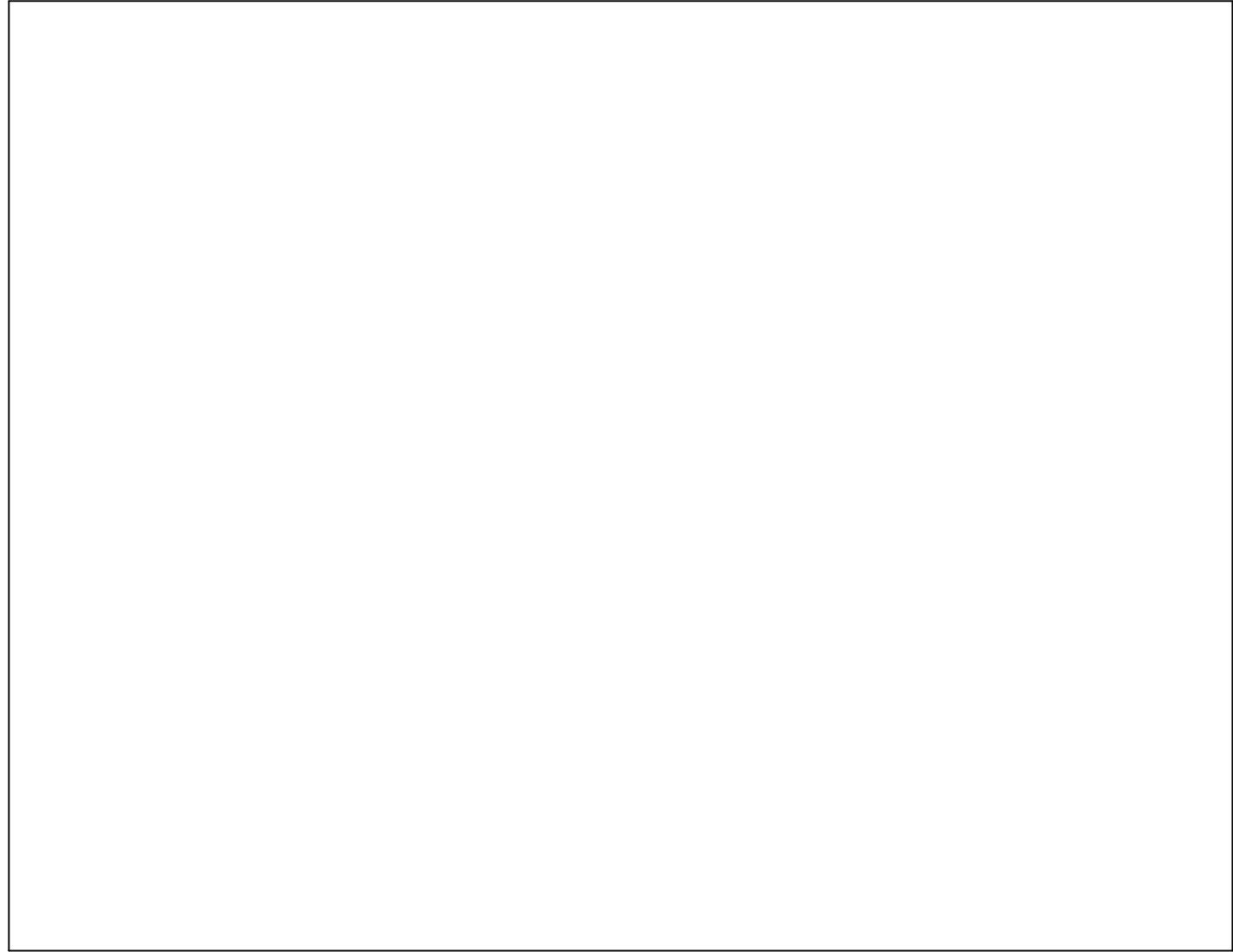
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00281		
PLOT NAME = Top Solder Mask	GENERATED : 10/23/2015 3:00:23 PM	TEXAS INSTRUMENTS	



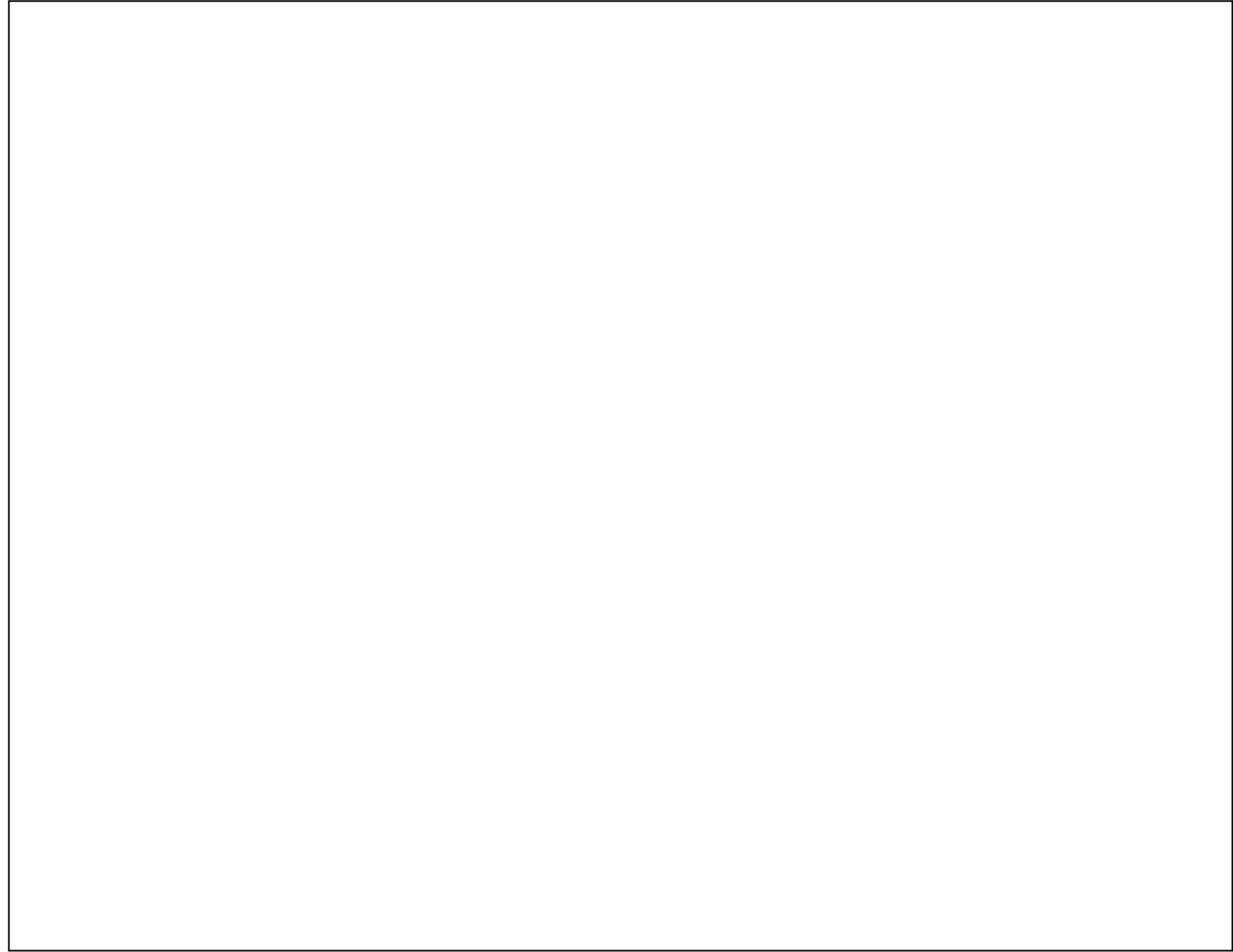
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00281		
PLOT NAME = Top Layer	GENERATED : 10/23/2015 3:00:25 PM	TEXAS INSTRUMENTS	



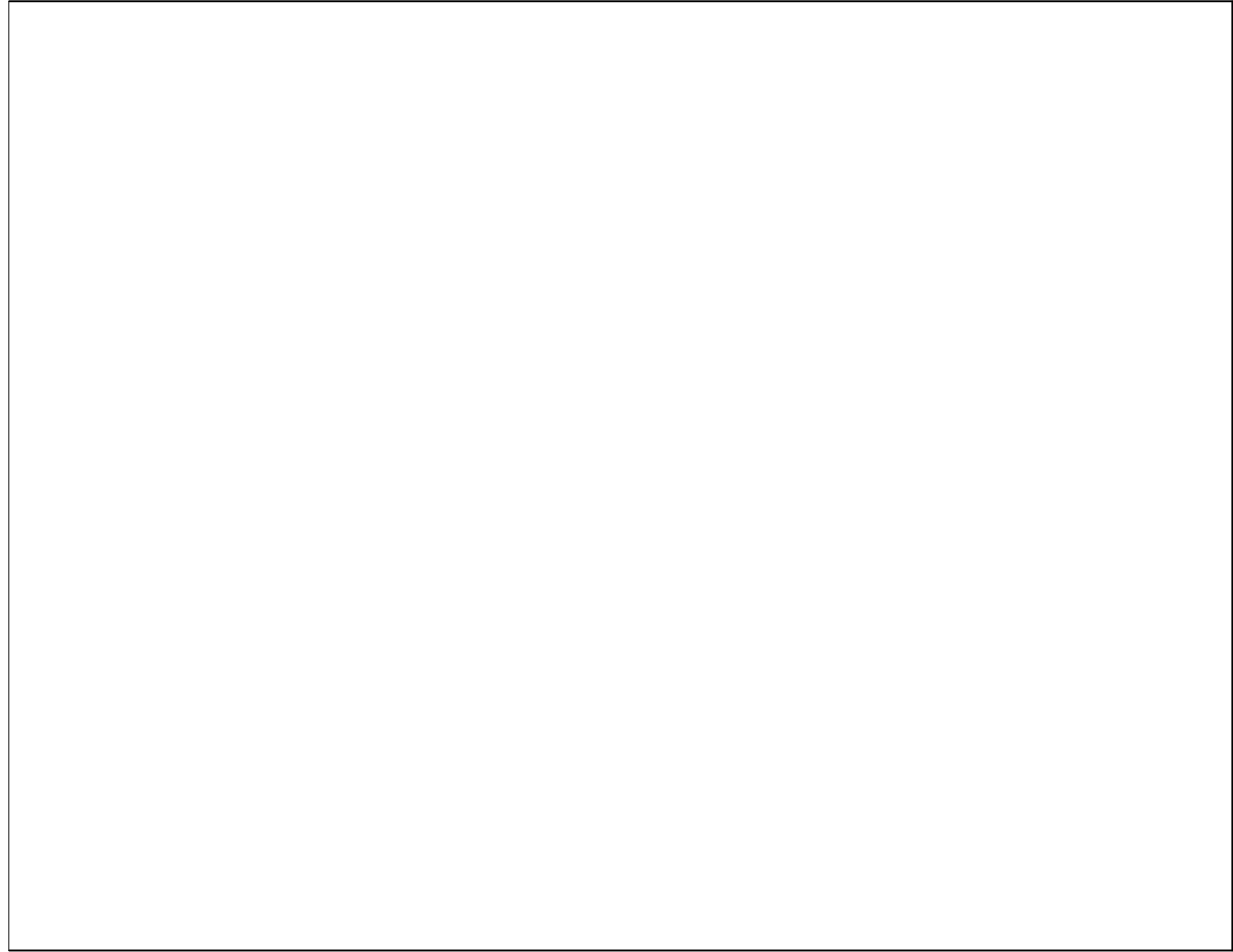
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3	TID #: TIDA-00281		
PLOT NAME = Signal Layer 1	GENERATED : 10/23/2015 3:00:26 PM		TEXAS INSTRUMENTS



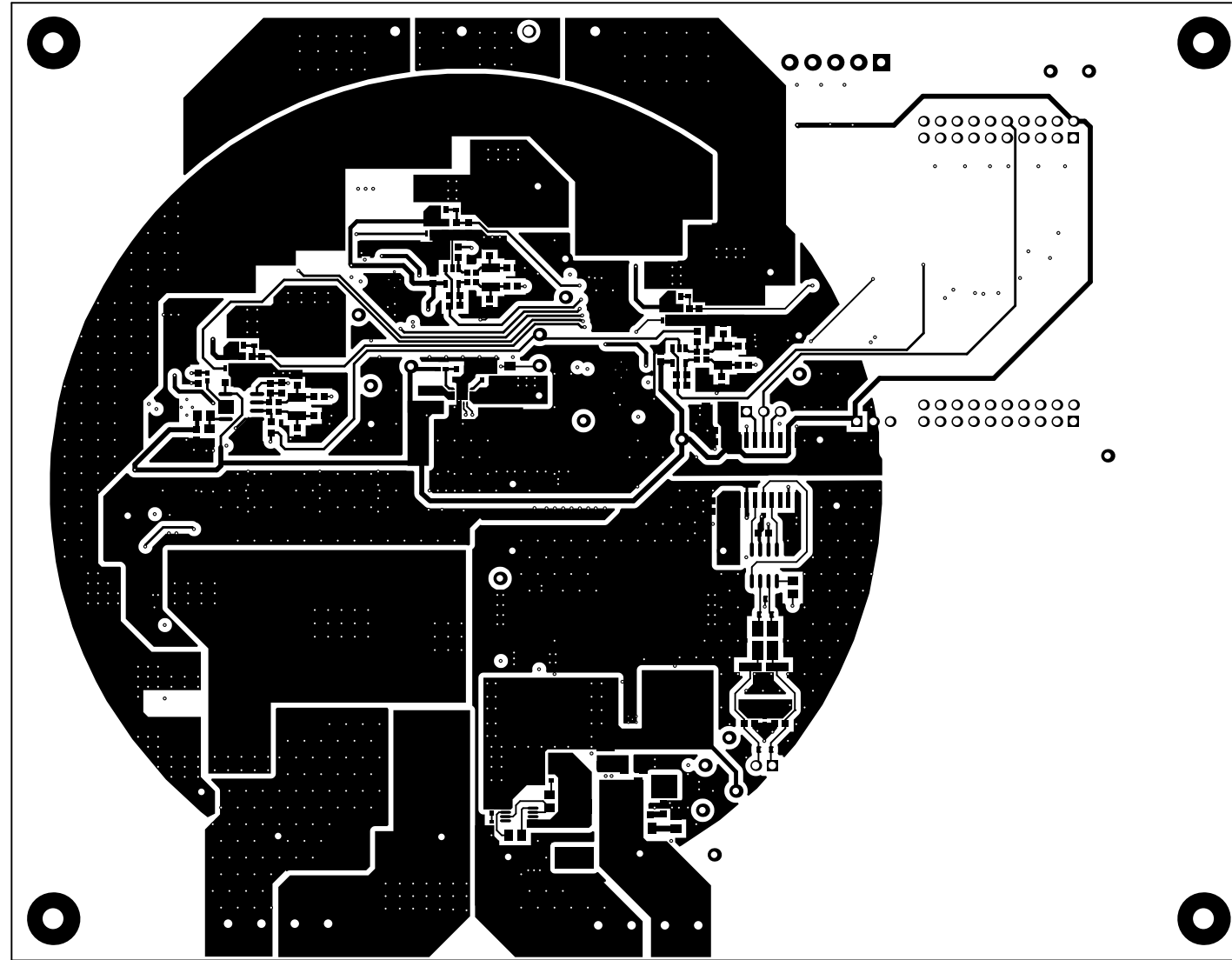
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00281		
PLOT NAME = Signal Layer 2	GENERATED : 10/23/2015 3:00:28 PM	TEXAS INSTRUMENTS	



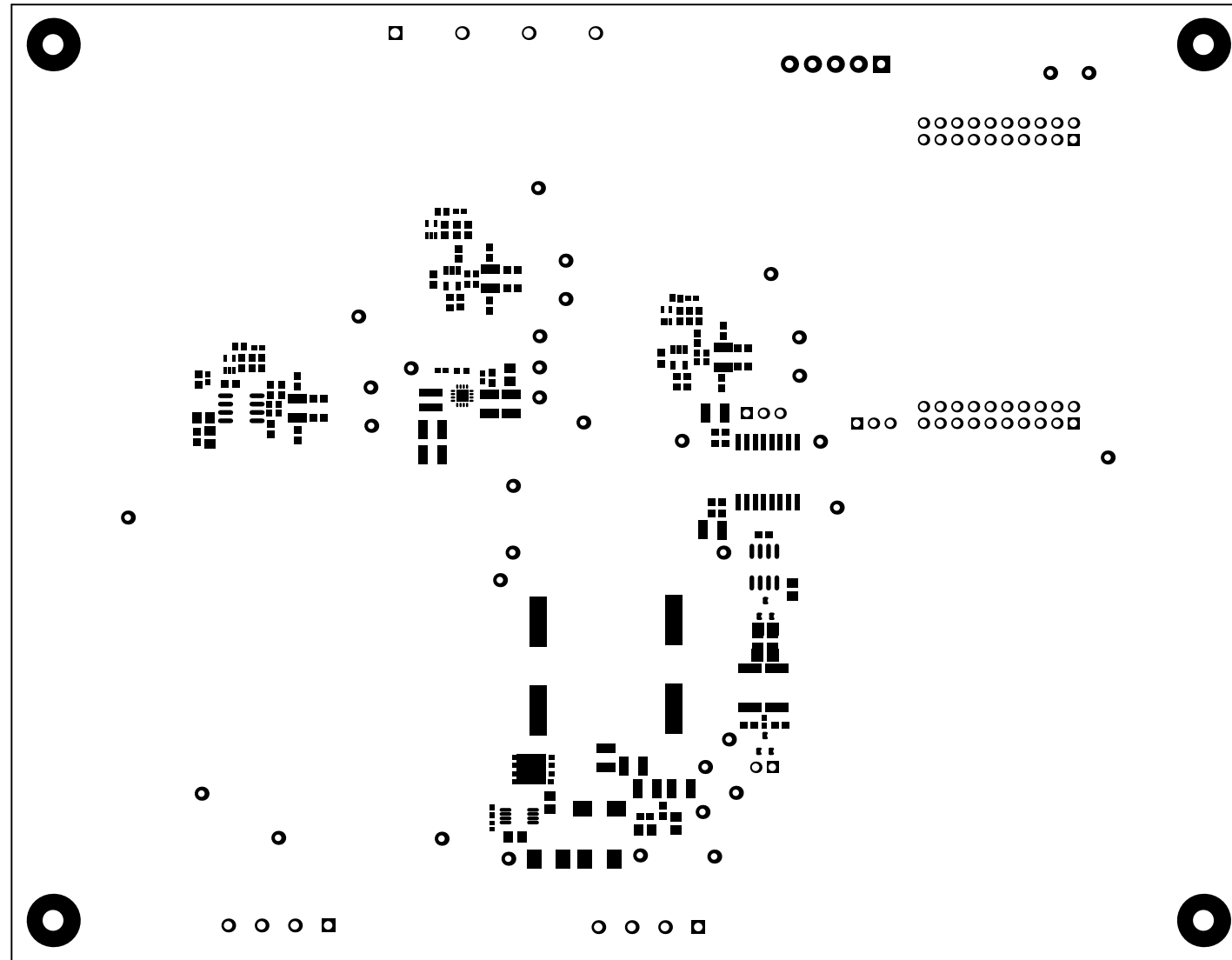
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00281		
PLOT NAME = Signal Layer 3	GENERATED : 10/23/2015 3:00:30 PM	TEXAS INSTRUMENTS	



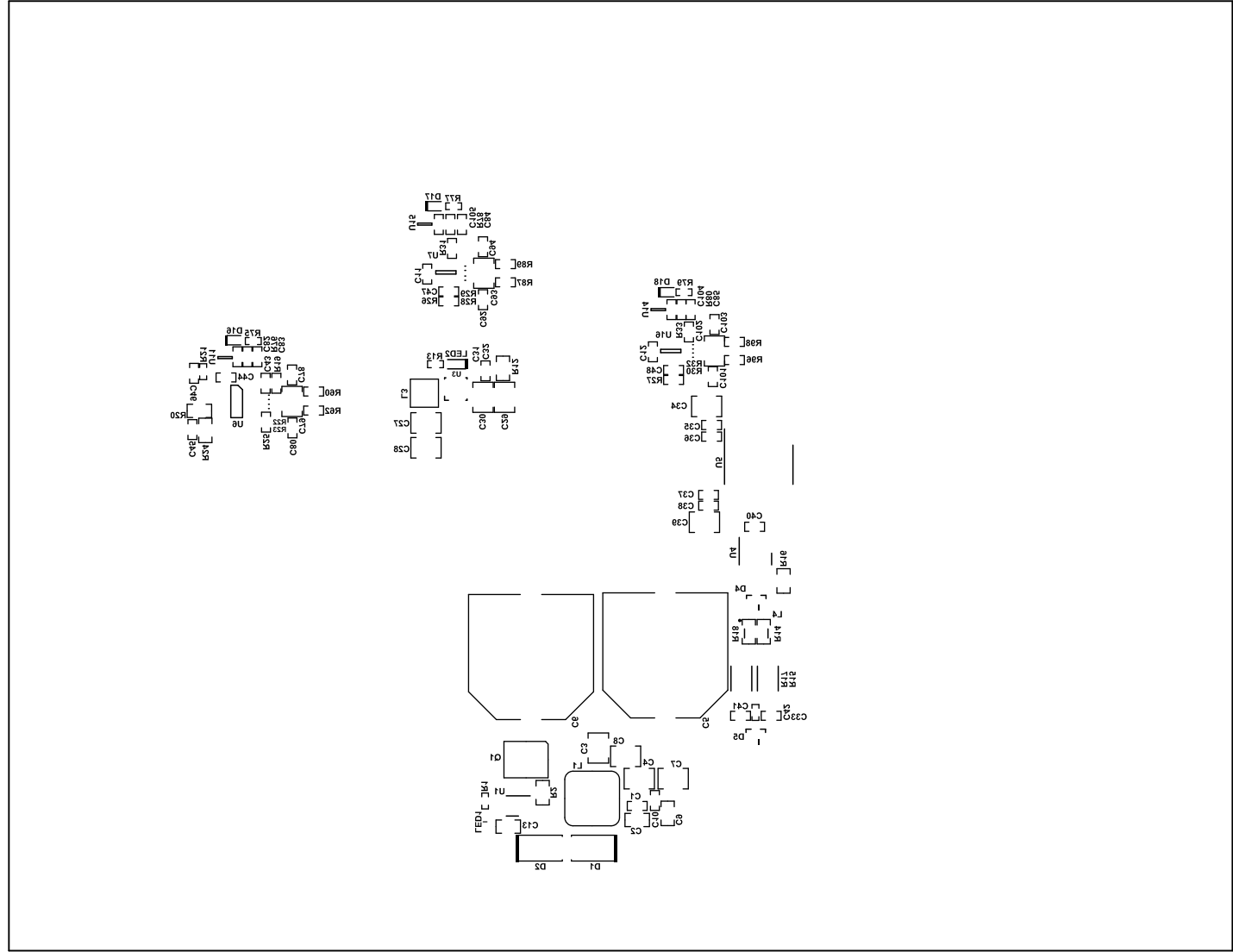
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00281		
PLOT NAME = Signal Layer 4	GENERATED : 10/23/2015 3:00:32 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00281		
PLOT NAME = Bottom Layer	GENERATED : 10/23/2015 3:00:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00281		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/23/2015 3:00:36 PM	TEXAS INSTRUMENTS	

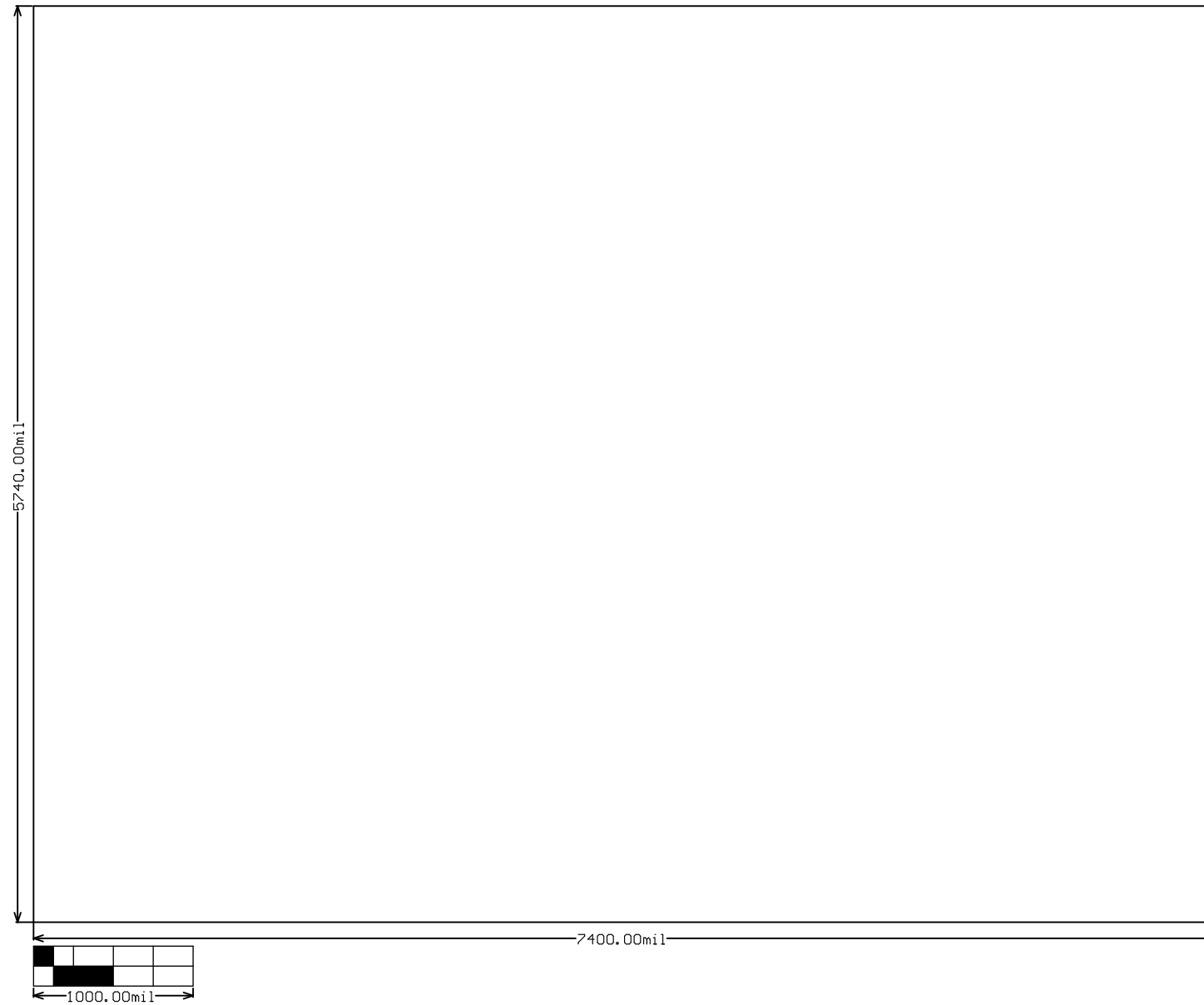


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00281		
PLOT NAME = Bottom Overlay	GENERATED : 10/23/2015 3:00:39 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	21	7.87mil (0.200mm)	PTH	Round
◇	837	12.00mil (0.305mm)	PTH	Round
▽	35	40.00mil (1.016mm)	PTH	Round
✱	48	45.28mil (1.150mm)	PTH	Round
⊗	5	50.00mil (1.270mm)	PTH	Round
⊕	8	52.00mil (1.321mm)	PTH	Round
⊗	4	59.06mil (1.500mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	962 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00281		
PLOT NAME = Drill Drawing	GENERATED : 10/23/2015 3:00:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00281		
PLOT NAME = Board Dimensions	GENERATED : 10/23/2015 3:00:44 PM	TEXAS INSTRUMENTS	

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